



PMB045T045SS-255A

2A/45V⁽¹⁾, low VF Planar MOS barrier diode

Mechanical Data

Chip Drawing	Item	Information	
<p>The chip drawing consists of two parts. The top part is a top-down view of a square die with dimensions A (height), B (width), and C (total height including scribe lines). A scribe line width E is indicated. The bottom part is a cross-sectional view showing the die thickness D, with layers labeled N (top), N* (middle), and Back Metal (bottom). The top metal is also labeled.</p>	Die Size (A)	1142μm	45.0 mil
	Top Metal Pad Size (B)	1042 μm	41.0mil
	Chip Size (C)	/	/
	Wafer Thickness (D)	255 μm	10.0 mil
	Scribe Line Width (E)	80 μm	3.15 mil
	Wafer Size	6 inch	
	Top Side Metallization	PMB045T045SS-255A	Ag
	Back Side Metallization	Ti Ni Ag	
	Recommended Storage Environment	Stored in original container, in dry nitrogen, (6 months at an ambient temperature of 23°C±3°C)	